

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Ganguli et al.

Serial No.: 10/811,230

Confirmation No.: 8995

Filed: March 26, 2004


For: Ruthenium Layer
Formation for Copper Film
Deposition

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Group Art Unit: 1762

Examiner: Kelly M. Stouffer

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF TRANSMISSION	
I hereby certify that this correspondence is being electronically transmitted to the U.S. Patent and Trademark Office via EFS-Web to the attention of Examiner Kelly M. Stouffer, on the date shown below.	
January 10, 2007	
Date	John-Paul F. Cherry

Dear Sir:

RESPONSE TO OFFICE ACTION DATED OCTOBER 10, 2006

In response to the Office Action dated October 10, 2006, having a shortened statutory period for response set to expire on January 10, 2007, please enter this Response and reconsider the claims pending in the application for the reasons discussed below. The attached fee transmittal form provides authorization to the Commissioner to charge the Applicant for the terminal disclaimer fee. Although the Applicant believes that no additional fees are due in connection with this Response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/005975.P2/JPC, for any fees, including extension of time fees or excess claim fees, required to make this Response timely and acceptable to the Office.

Amendments to the Specification begin on page 2 of this paper. **Amendments to the Claims** begin on page 11 of this paper. **Amendments to the Drawings** begin on page 21 of this paper and include both an attached replacement sheet and an annotated sheet. **Remarks** begin on page 22 of this paper.